### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1

EPAS ID: PAT5859649 Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
KENTARO AKIYAMA	11/26/2019
TAKUMA MATSUNO	11/28/2019
TAKASHI TERADA	11/28/2019
TOMOHIRO YAMAZAKI	11/26/2019

#### **RECEIVING PARTY DATA**

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO, ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	243-0014

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16615884

#### **CORRESPONDENCE DATA**

Fax Number: (414)277-0656

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 414-271-6560

Email: DCipdocket@michaelbest.com

**Correspondent Name:** MICHAEL BEST & FRIEDRICH LLP (SONY)

Address Line 1: 100 E WISCONSIN AVENUE

Address Line 2: **SUITE 3300** 

Address Line 4: MILWAUKEE, WISCONSIN 53202

ATTORNEY DOCKET NUMBER:	880005-6577-US01
NAME OF SUBMITTER:	CHRISTOPHER M. TOBIN
SIGNATURE:	/Christopher M. Tobin/
DATE SIGNED:	12/10/2019
	This document serves as an Oath/Declaration (37 CFR 1.63).
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**Total Attachments: 4** 

source=27127029\_880005-6577-US01\_Declaration\_and\_Assignment#page1.tif source=27127029\_880005-6577-US01\_Declaration\_and\_Assignment#page2.tif source=27127029\_880005-6577-US01\_Declaration\_and\_Assignment#page3.tif source=27127029\_880005-6577-US01\_Declaration\_and\_Assignment#page4.tif

Attorney Docket No.: Sony Ref. No.: SP368153US00

## DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention IMAGING ELEMENT AND SOLID-STATE IMAGING DEVICE		
As the below named inventor, I hereby declare that:		
This declaration is directed to:  The attached application, or		
United States application or PCT international application number PCT/JP2018/6 filed on 2018/04/18	015969	
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.  WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION	with offices at	
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under a legal protection which may be granted therefor in the United States and in any and all foreign countries;	ASSIGNEE), is desirous of my Letters Patent or similar	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, legal representatives, the entire right, title and interest in said invention, said application, including any divisions an in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for sany and all priority rights and/or convention rights under the International Convention for the Protection of Industri Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents of United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;	its successors, assigns, and discontinuations thereof, and aid invention, and in and to all Property, Inter-American the United States of America or securing of patents in the	
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applie the United States and countries foreign thereto;	to me and without further	
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR	e 4 \$	
Inventor: KENTARO AKIYAMA Date: 2005	11/36	
Signature: Kontoro Akitama		

Attorney Docket No.: Sony Ref. No.: SP368153US00

# DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	IMAGING ELEMENT AND SOLID-STATE IMAGING DEVICE	
As the below	named inventor; I hereby declare that:	
This declaration is directed to:	The attached application, or	
	United States application or PCT international application number PCT/JP2018/015969 filed on 2018/04/18	
	miffied application was made or authorized to be made by me.	
WHEREAS,	I am the original inventor or an original joint inventor of a claimed invention in the application.  SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at	
	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
acquiring all i legal protection	nterest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar in which may be granted therefor in the United States and in any and all foreign countries;	
of which are legal represent in and to any any and all proposition Radheres, and funited States	FORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and tatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to ionly rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American clating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America is any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters ASSIGNEE, as the assignee of the whole right, title and interest thereto;	
remuneration,	agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of ites and countries foreign thereto;	
application for	agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for reforeign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;	
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknows than	owledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of live (5) years, or both.	
LEGAL NAM	E OF INVENTOR	
Inventor:	takuma matsuno Date: 20/7/1:/2}	
Signature:	takuma matsuno	

Attorney Docket No.: Sony Ref. No.: SP368153US00

## DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	IMAGING ELEMENT AND SOLID-STATE IMAGING DEVICE	
As the below	named inventor, I hereby declare that:	
This declarati	The market word and a second	
	United States application or PCT international application number PCT/JP2018/015969 filed on 2018/04/18	
	entified application was made or authorized to be made by me.	
I believe that WHEREAS,	I am the original inventor or an original joint inventor of a claimed invention in the application.  SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at	
~~~~~~~	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, self and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filting of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignce of the whole right, title and interest thereto;		
designee, as remuneration	ragree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of ates and countries foreign thereto;	
application is	r agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for or foreign patents, for filting subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;	
And I further agree that ASSIGNEB will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NA	ME OF INVENTOR	
Investor:	TAKASHI TERADA Date: 28 (9 / 11 / 28	
Signature:	TAKASHI TERADA	

### DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention IMAGING ELEMENT AND SOLID-STATE IMAGING DEVICE		
As the below named inventor, I hereby declare that:		
This declaration		
United States application or PCT international application number PCT/JP2  filed on 2018/04/18  The above-identified application was made or authorized to be made by me.	2018/015969	
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.		
WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION	, with offices at	
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referre acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and u	d to as ASSIGNEE), is desirous of	
legal protection which may be granted therefor in the United States and in any and all foreign countries;	adds any section carein in sometim	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consider of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIG legal representatives, the entire right, title and interest in said invention, said application, including any division and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted any and all priority rights and/or convention rights under the International Convention for the Protection of Ir Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to we adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patchised States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents Patent to said ASSIGNEE, as the assignce of the whole right, title and interest thereto;	NEE, its successors, assigns, and one and continuations thereof, and if for said invention, and in and to adustrial Property, Inter-American nich the United States of America stents or securing of patents in the	
And I further agree to execute all necessary or desirable and lawful future documents, including assignme designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time premuneration, in order to perfect title in said invention, modifications, and improvements in said invention, the United States and countries foreign thereto;	esent to me and without further	
And I further agree to properly execute and deliver and without further remaneration, such necessary or application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any Patent which may be gramed for my aforesaid invention, as said ASSIGNEE thereof shall be ceafter require at	reissue or reissues of any Letters	
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby coverant that no assignment, sale, agreement or encumbrance has been or will be made or enter this assignment and sale.	ed into which would conflict with	
I bereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C not more than five (5) years, or both.	. 1001 by fine or imprisonment of	
LEGAL NAMÉ OF INVENTOR	A Lac Im P	
Inventor: TOMOHIRO YAMAZAKI Date: 20	1/11/26	
Signature: TOMOHTRO TAMAZAKI		

**RECORDED: 12/10/2019**